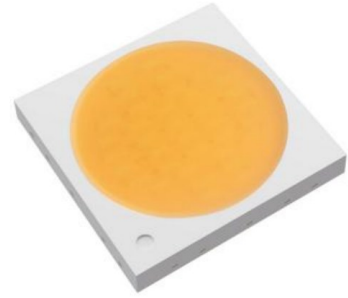


EMC-7070DV66W-B2C14-S1-HR5-Y2-P6

Features(特征)

- PLCC-2 Package.(PLCC-2 封装)
- Extremely wide viewing angle. (宽的发光角度)
- Suitable for all SMT assembly and solder process. (适用于所有的SMT组装和焊接工艺)
- Available on tape and reel. (适用于载带及卷轴)
- Moisture sensitivity level: Level 4. (防潮等级 Level 4)
- Package:1000pcs/reel..(包装每卷1000PCS)



Description (描述)

The White LED which was fabricated using a blue chip and the phosphor
白光LED由蓝光芯片与荧光粉激发而成

After the product life cycle for recycling
产品生命周期后进行回收处理



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

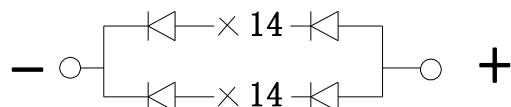
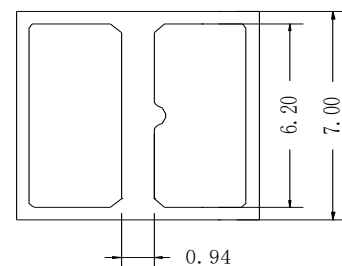
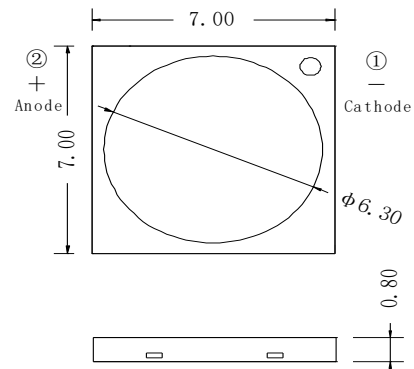
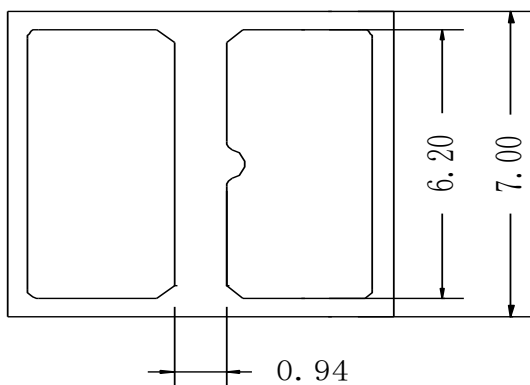
注意：操作时应注意静电敏感
释放设备装置

Package Dimensions (封装尺寸)

Applications (应用)

- Portable lighting (便携照明)
- Decorative lighting (装饰照明)
- OA equipment (办公照明)
- Backlighting of full color LCD (液晶背光)
- Bulbs and fluorescent lamps (家居照明)

Recommended Soldering Pattern (建议焊盘尺寸图)



Notes: (备注)

1. All dimension units are millimeters. (所有标注尺寸单位为毫米)
2. All dimension tolerance is $\pm 0.15\text{mm}$ unless otherwise noted. (除特别标注外，所有尺寸允许公差 $\pm 0.15\text{mm}$)

EMC-7070DV66W-B2C14-S1-HR5-Y2-P6

Selection Guide (选择指南)

Part No. 型号	Chip Materials 芯片材料	Lens Type 胶体类型
EMC-7070DV66W-B2C14-S1-HR5-Y2-P6	InGaN	Yellow Diffused

Mass Production list (批量生产目录)

Part No. 型号	CCT (K) Typ	Φ (lm) Min	Φ (lm) Typ	Test Conditions 测试条件
EMC-7070DV66W-B2C14-S1-HR5-Y2-P6	2700	1150	1250	IF=45mA
	3000	1250	1350	IF=45mA
	3500	1250	1350	IF=45mA
	4000	1250	1350	IF=45mA
	5000	1350	1450	IF=45mA
	5700	1350	1450	IF=45mA
	6000	1350	1450	IF=45mA
	6500	1350	1450	IF=45mA

Electrical / Optical Characteristics at Ta=25°C 电性与光学特性

Parameter (参数)	Symbol (符号)	Min. (最小)	Typ. (平均)	Max. (最大)	Units (单位)	Test Conditions 测试条件
Forward Voltage 正向电压	VF	240	245	250	V	IF=45mA
Viewing Angle 角度	2 θ 1/2	--	120	--	Deg	IF=45mA
Color Rendering Index 显色性指数	Ra	90	--	--	--	IF=45mA
Saturated red 红色饱和度	R9	50	--	--	--	IF=45mA

Note:(备注)

- 2 θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2 θ 1/2 是半值角, 指光强是光学中心线光强的1/2处到光学中心线的角度
- The above luminous flux measurement allowance tolerance is $\pm 10\%$.
上述光通量的测试允许公差为 $\pm 10\%$
- The above Color Rendering Index measurement allowance tolerance is ± 2
以上显色性指数的测试允许公差为 ± 2
- The above forward voltage measurement allowance tolerance is ± 3 .
以上所示电压测量误差 ± 3
- The above color coordinates measurement allowance tolerance is ± 0.01 .
以上所示坐标测量误差 ± 0.01

EMC-7070DV66W-B2C14-S1-HR5-Y2-P6

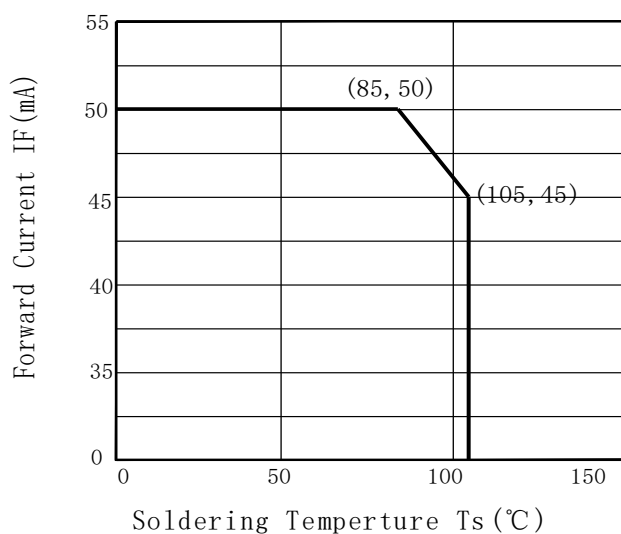
Absolute Maximum Ratings at Ta=25°C 绝对最大额定值

Parameter (参数)	Symbol (符号)	Rating (值)	Units (单位)
Power Dissipation (功耗)	Pd (IF=50mA)	12	W
Forward Current (正向电流)	IF	50	mA
Reverse Current 反向电流	IR	10	μA
Electrostatic Discharge (HBM) (静电)	ESD	2000	V
Operating Temperature (操作温度)	Topr	-35 ~ +85	℃
Storage Temperature (保存温度)	Tstg	-35 ~ +85	℃
Junction Temperature结温	Tj	125	℃

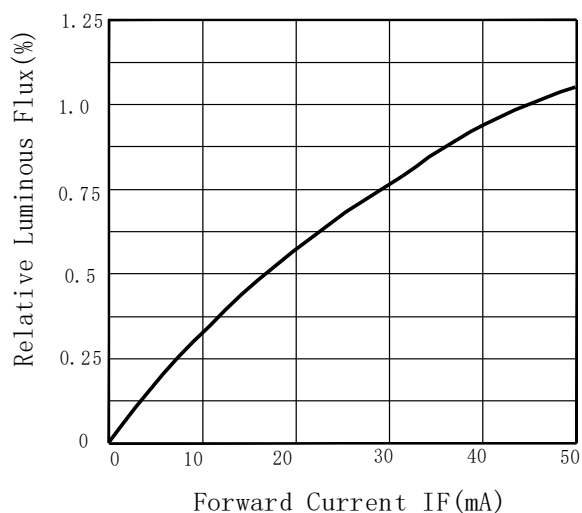
EMC-7070DV66W-B2C14-S1-HR5-Y2-P6

characteristics curves 特性曲线

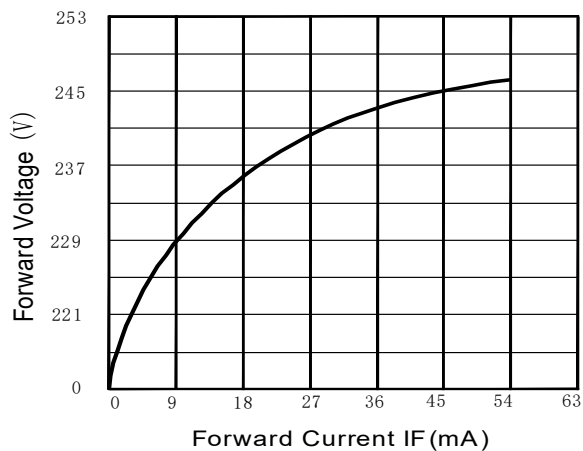
Soldering Temperature vs. Forward Current
焊盘温度与正向电流特性曲线



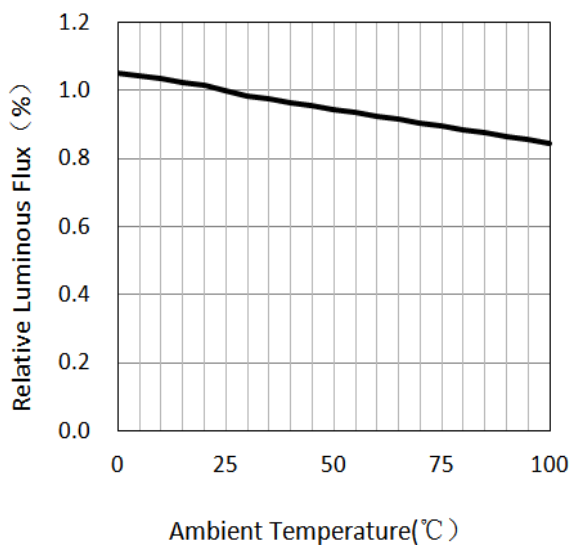
Forward Current VS. Relative Intensity
正向电流与相对光强特性曲线



Forward Voltage VS. Forward Current
正向电压与正向电流特性曲线

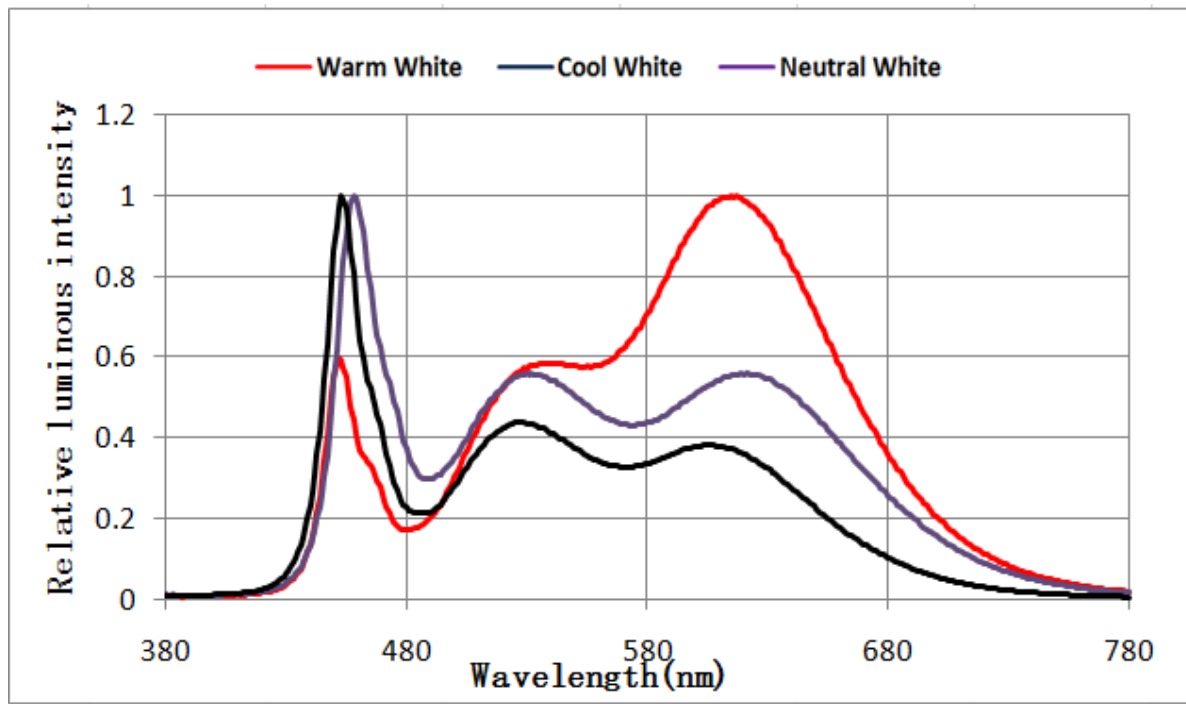


Ambient Temperature VS. Relative Intensity
环境温度与相对光强特性曲线

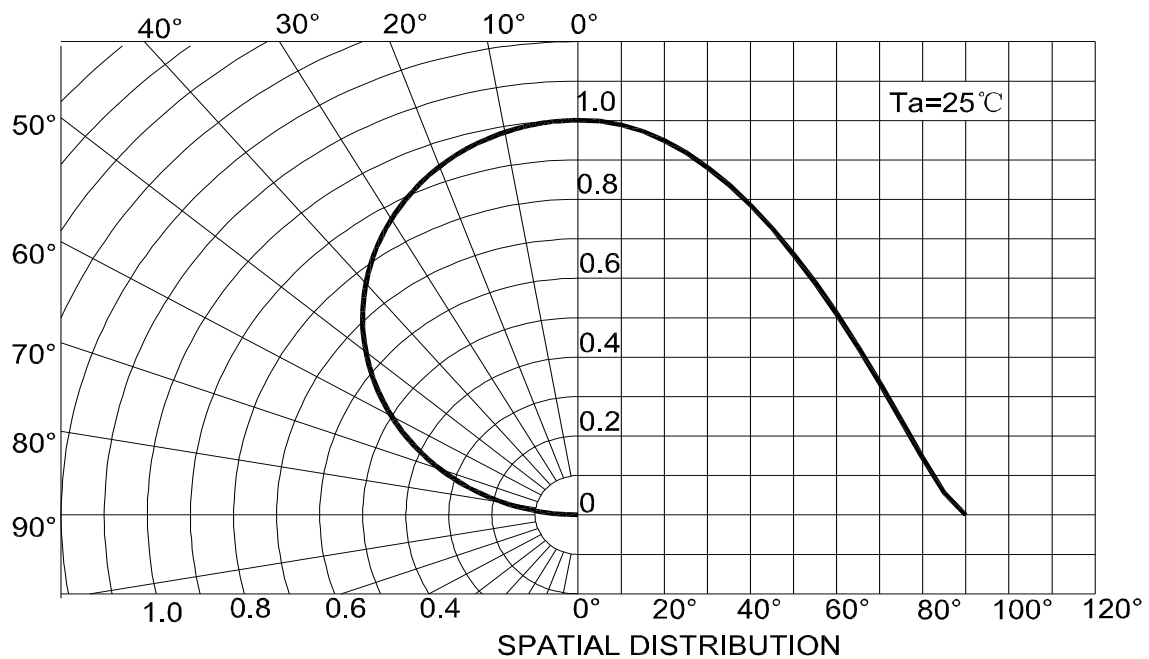


EMC-7070DV66W-B2C14-S1-HR5-Y2-P6

Typical optical characteristics curves 典型光学特性曲线

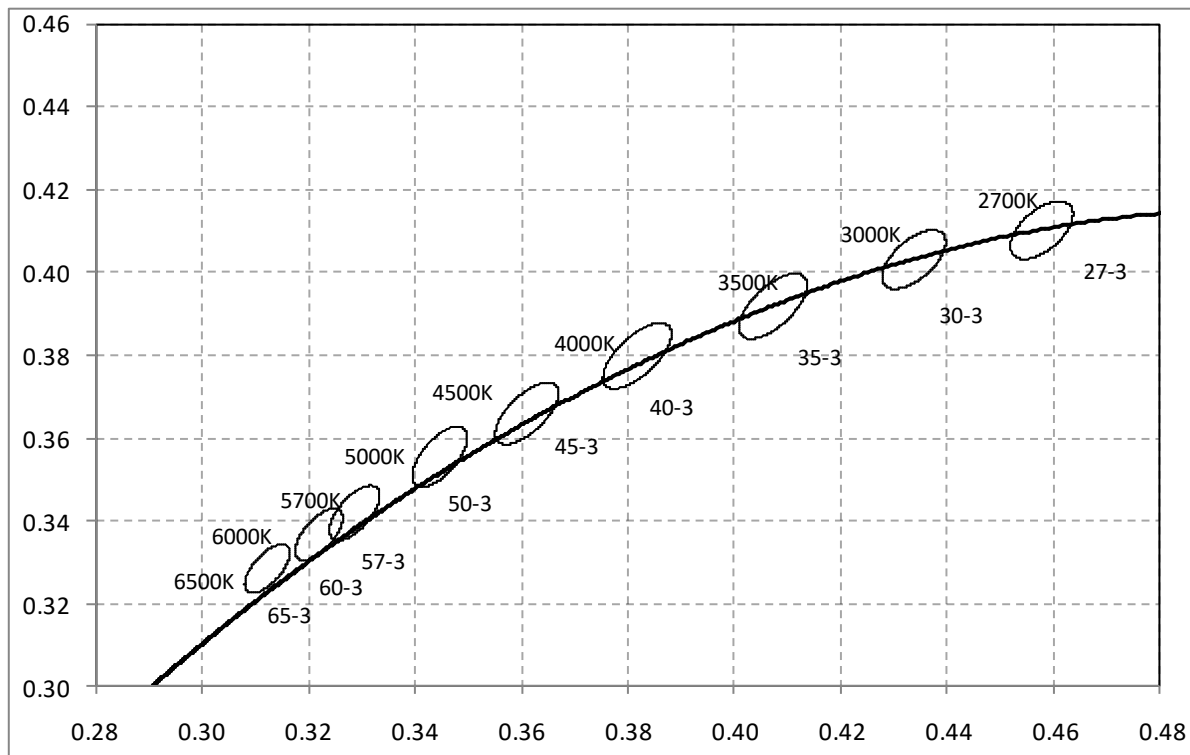


Radiation diagram 辐射图特性曲线



EMC-7070DV66W-B2C14-S1-HR5-Y2-P6

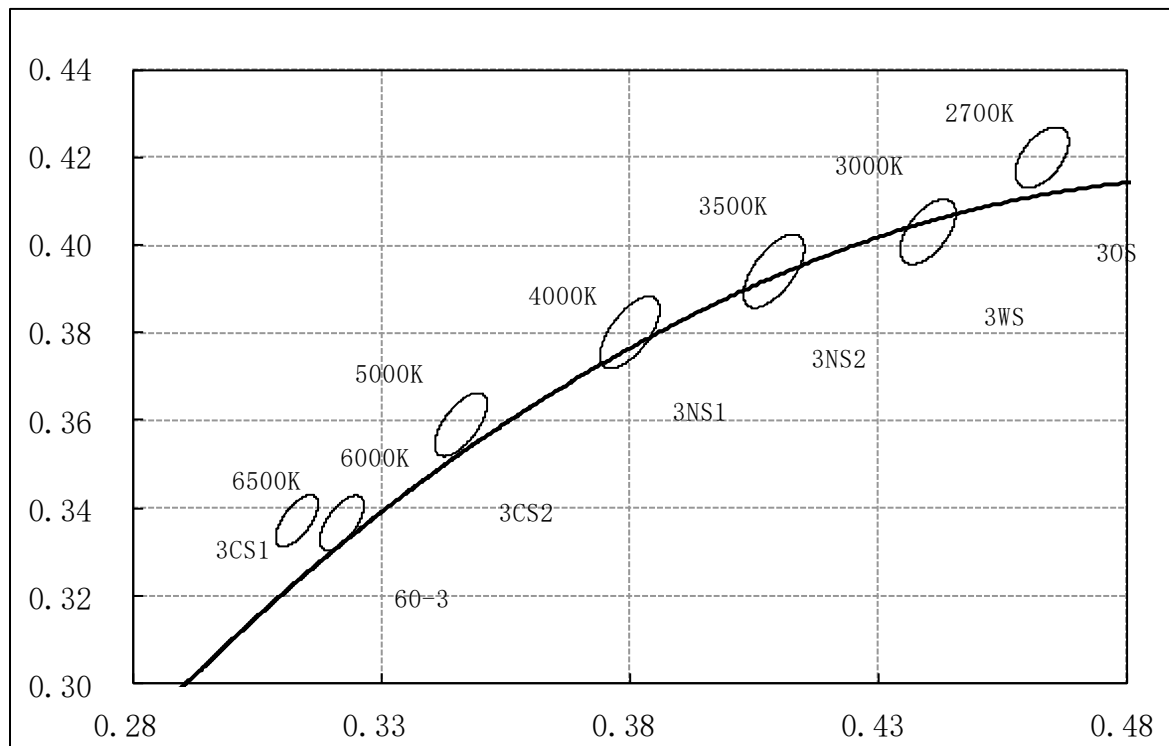
Bin Range of Chromaticity Coordinate Bin区分类及色坐标范围



Bin Range of Chromaticity Coordinate Bin区分类及色坐标范围

CCT 色温	Bin Code Bin代码	CIE_x	CIE_y	a	b	Θ
6500K	65-3	0.3123	0.3282	0.00669	0.00285	58.57
6000K	60-3	0.3220	0.3365	0.00708	0.00302	59.21
5700K	57-3	0.3287	0.3417	0.00746	0.00320	59.09
5000K	50-3	0.3447	0.3553	0.00822	0.00354	59.62
4500K	45-3	0.3611	0.3658	0.00881	0.00378	54.35
4000K	40-3	0.3818	0.3797	0.00939	0.00402	53.72
3500K	35-3	0.4073	0.3917	0.00927	0.00414	54.00
3000K	30-3	0.4338	0.4030	0.00834	0.00408	53.22
2700K	27-3	0.4578	0.4101	0.00810	0.00420	53.7

EMC-7070DV66W-B2C14-S1-HR5-Y2-P6

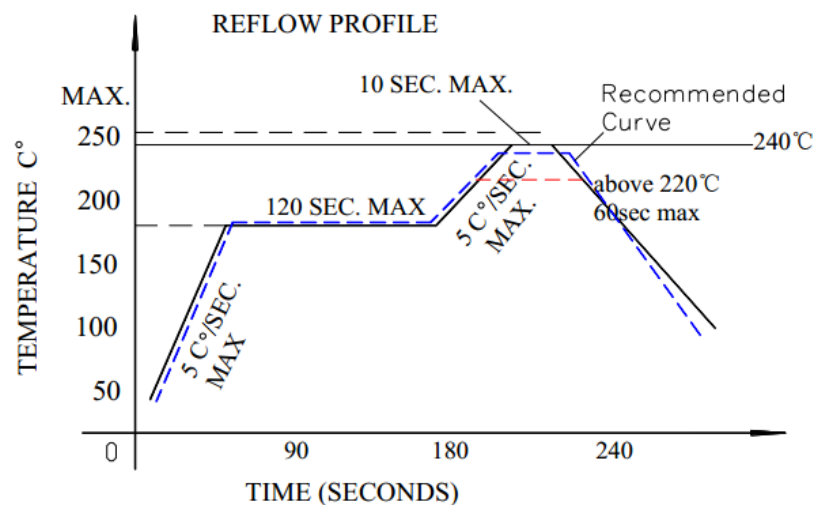


ERP Bin Range of Chromaticity Coordinate 欧标Bin区分类及色坐标范围

Nominal CCT	Bin Code	Target Center Point (cx,cy)	Major Axis, a	Major Axis, b	Ellipse Rotation Angle, θ	Color Space
6500K	3CS1	0.313,0.337	0.00669	0.00285	58.23°	Sing 3-step
6000K	60-3	0.3220,0.3365	0.00708	0.00302	59.21	Sing 3-step
5000K	3CS2	0.346,0.359	0.00822	0.00354	59.37°	Sing 3-step
4000K	3NS1	0.380,0.380	0.00939	0.00402	54.00°	Sing 3-step
3500K	3NS2	0.409,0.394	0.00951	0.00417	52.58°	Sing 3-step
3000K	3WS	0.440,0.403	0.00834	0.00408	53.10°	Sing 3-step
2700K	3OS	0.463,0.420	0.00774	0.00411	53.17°	Sing 3-step

EMC-7070DV66W-B2C14-S1-HR5-Y2-P6

SMT Reflow Soldering Instructions SMT回流焊说明



1.Reflow soldering should not be done more than three times. 回流焊不可以做三次以上。

2.When soldering, do not put stress on the LEDs during heating

当焊接时，不要在材料受热时用力压胶体表面。

Soldering iron 烙铁焊接

1.When hand soldering, keep the temperature of iron below less 350℃ less than 5 seconds

当手工焊接时，烙铁的温度必须小于350℃，时间不可超过5秒。

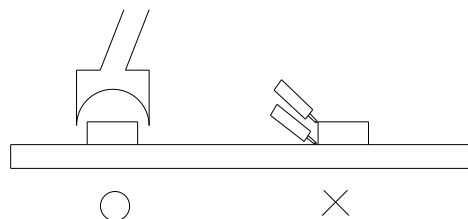
2.The hand solder should be done only one times

手工焊接只可焊接一次。

Repairing 修补

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or will not be damaged by repairing.

LED回流焊后不应该修复，当修复是不可避免时，必须使用双头烙铁（如下图），但必须事先确认此种方式会或不会损坏LED本身的特性。



Cautions 注意事项

The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be influence to the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use the picking up nozzle, the pressure on the silicone resin should be proper.

LED封装为硅胶，故LED胶体表面较软，用力按压胶体表面会影响LED可靠性，因此应有预防措施避免在封装的零件上的强大压力，当使用吸嘴时，胶体表面的压力应是恰当的。

EMC-7070DV66W-B2C14-S1-HR5-Y2-P6

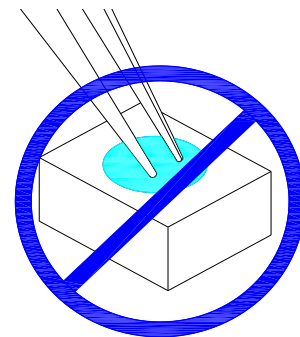
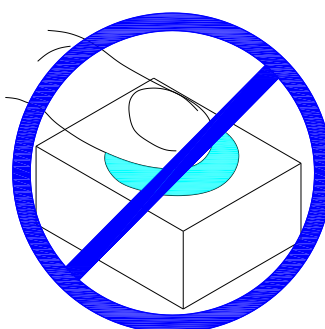
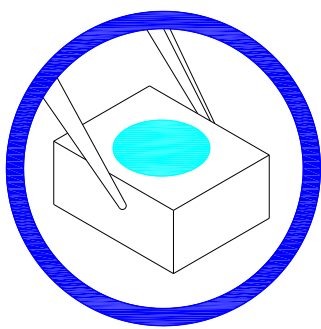
Handling Precautions 处理防备措施

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more prone to damage by external mechanical force. As a result, Special handling precautions must be observed during assembling using silicone encapsulated LED products, Failure to comply might leads to damage and premature failure of the LED.

相对环氧树脂较脆较硬而言，硅胶封装较柔软且有弹性，虽然它的特性大大减少了热应力，但易受机械外力损坏，因此在手工处理方面须要对硅胶封装材料做预防措施，若未按要求操作，可能会导致LED损坏和光衰。

1.Handle the component along the side surface by using forceps or appropriate tools; do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.

通过使用适当的工具从材料侧面夹取，不可直接用手或尖锐金属压胶体表面，它可能会损坏内部电路。



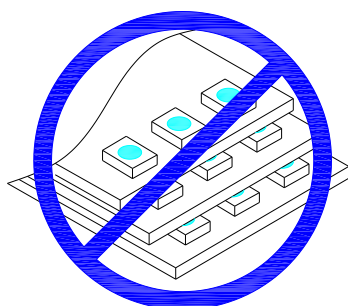
2.The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.

为防止气压泄漏，SMD吸咀外径不可以超过LED尺寸，吸咀内径尺寸应尽可能大，吸咀顶端材质建议采用柔软材料以防在吸取期间刮伤或损坏LED胶体表面，元件的尺寸必须在取放机里准确的编程好，以确保精确的吸取和避免生产过程中的损害。



3.Do not stack together assembled PCBs containing LEDs. Impact may scratch the silicone lens or damage the internal circuitry

不可将模组材料堆积在一起，它可能会损坏内部电路。



4.Not suitable to operate in acidic environment, PH<7

不可用在PH<7的酸性场所。

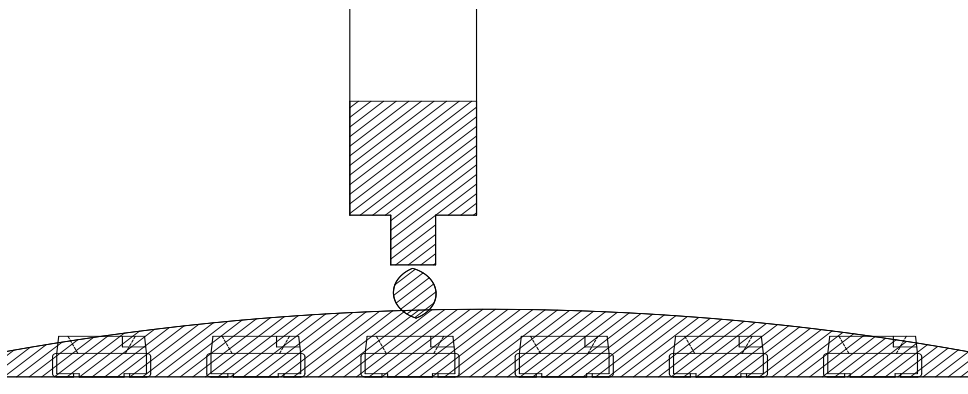


5.LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material.

LED工作环境及与LED适配的材料中硫元素及化合物成份不可超过100PPM。

6.When we need to use external glue for LED application products, please make sure that the external glue matches the LED packaging glue. Additionally ,as most of LED packaging glue is silica gel, and it has strong Oxygen permeability as well as strong moisture permeability; in order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM,the single content of Chlorine element is required to be less than 900PPM,the total content of Bromine element and Chlorine element in the external glue of the application products is required to be less than 1500PPM

当我们需要使用外封胶涂抹LED产品时，应确保外封胶与LED封装胶水相匹配，因为大多数LED的封装胶水为硅胶，它有较强的氧化性和较强的吸湿性，必须防止外封材质进入LED内部以造成LED的损伤，单一的溴元素含量要求小于900PPM，单一氯元素含量要求小于900PPM，在涂抹LED产品时要求外封胶溴元素与氯元素总含量必须小于1500PPM。



7.Other points for attention, please refer to our LED user manual , In accordance with the user manual, the product shelf life is 24 months , If there is a warranty agreement, the warranty agreement shall prevail

其它注意事项请参照我们的LED使用手册，符合使用手册的情况下，产品保质期为24个月，已签订保质协议的则以保质协议为准

EMC-7070DV66W-B2C14-S1-HR5-Y2-P6

Label 标签

PartNo: Part number	型号
ΦV: Luminous intensity rank	亮度等级
VF: Forward voltage rank	电压等级
X/Y: Coordinate rank	色坐标
TC: Color temperature	色温
LotNo: Lot number	批号
LotNo: Lot number	工单号


HONGLI TRONIC
鸿利光电


PartNo:

ΦV:

VF:

X/Y:

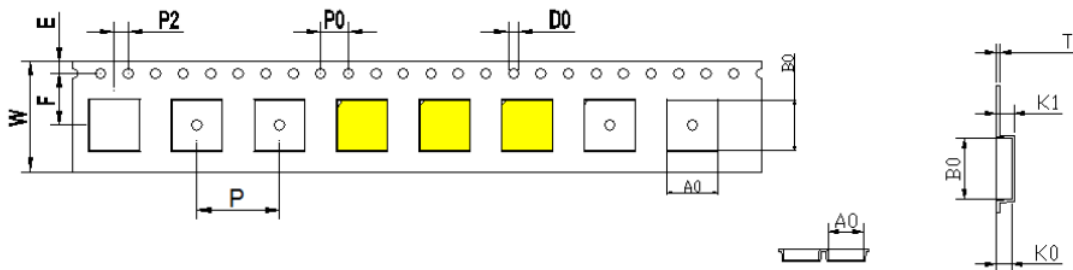
TC:

Qty:

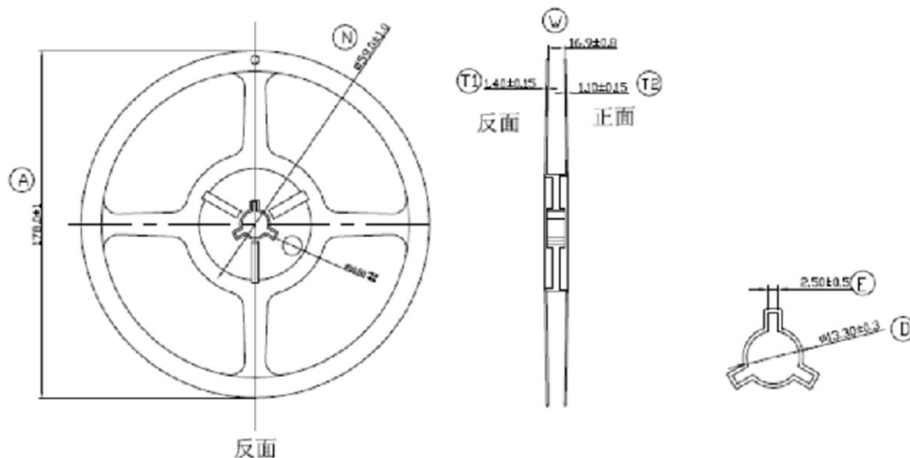
LotNo:



Reel Packaging(包装)



symbol	AO	BO	KO	PO	P	P2	长度/盘
Spec	7.30±0.1	7.30±0.1	1.00±0.1	4.00±0.10	12.0±0.1	2.00±0.10	200M/R
symbol	W	T	E	F	DO	D1	K1
Spec	16.0±0.3	0.25±0.05	1.75±0.10	7.5±0.1	1.50 ^{+0.1} ₋₀	1.50±0.10	1.20±0.1



NOTES 备注:

- Empty component pockets are sealed with top cover tape;
预留载带空位也贴有上封带
- The maximum number of missing lamps is two;
最多缺失的 LED 不能超过两颗
- The cathode is oriented towards the tape sprocket hole in accordance with ANSI/EIA RS-481 specifications.
根据 ANSI/EIA RS-481 的规格,产品的负极指向卷带的导孔.
- Package for 7070, 1KPCS/roll
7070 包装, 1K/卷

修订次数	修订人	修订内容	修订日期	版次
1	曾忠祥	新建文件	2025. 3. 31	A/0
2	王芝烨	1、最大功率由11. 2W改为12W, 最大电流45mA改为50mA 2、修改特性曲线	2025.11. 20	A1
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